

3.5.2 EEPROM, Word Wide

Release 1

3.5.2.1 - 4K TO 32K BY 16 EEPROM IN DIP

CAPACITY--4K TO 32K WORDS OF 16 BITS,
PACKAGE--40 PIN DIP, 0.6" WIDE
PIN ASSIGNMENTS--Fig. 3.5.2-1

3.5.2.2 - 4K TO 256K BY 16 EEPROM IN SCC

CAPACITY--4K TO 256K WORDS OF 16 BITS,
PACKAGE--44 PAD (PIN) RCC, 0.650" X 0.650"
PIN ASSIGNMENTS--Fig. 3.5.2-2

3.5.2.3 - 256K TO 128M BY 16 EEPROM IN DIP AND SOP

CAPACITY--256K, 512K, 1M, 2M, 4M, 8M, 16M, 32M, 64M, and 128M WORDS OF 16 BITS
PACKAGE--44, 48 or 52 PIN DIP and SOP, 0.600" WIDE
PIN ASSIGNMENTS--256K TO 2M, Fig. 3.5.2-4
PIN ASSIGNMENTS--4M TO 128M, Fig. 3.5.2-3

3.5.2.4 - 1M TO 4M BY 16 DUAL SUPPLY EEPROM IN SSOP

CAPACITY--1M, 2M, 4M WORDS OF 16 BITS,
PACKAGE--56PIN SSOP, 13.5 mm WIDE, 0.8 mm PIN PITCH
PIN ASSIGNMENTS--Fig. 3.5.2-5

3.5.2.5 - 1M, 2M, & 4M DENSITY, BY 8 & 16 EEPROM IN PSOP

CAPACITY--1M, 2M, & 4M, BITS WITH x8 OR x16 DATA INTERFACE.
--128K, 256K, OR 512K WORDS OF 8 BITS
--64K, 128, OR 256K WORDS OF 16 BITS
PACKAGE--44 PIN PSOP, 16 mm WIDE
PIN ASSIGNMENTS--Fig. 3.5.2-6
POWER SUPPLIES--SINGLE OR DUAL SUPPLY DESIGN

3.5.2.6 - 1M TO 32M DENSITY, BY 8 & 16 EEPROM IN TSOP1

CAPACITY--1M, 2M, 4M, 8M, 16M, & 32M BITS WITH x8 OR x16 DATA INTERFACE.
--128K, 256K, 512K, 1M, 2M, OR 4M WORDS OF 8 BITS
--64K, 128, 256K, 512K, 1M, OR 2M WORDS OF 16 BITS
PACKAGE--44 PIN TSOP1, 20 mm X 16 mm with 0.5 mm PP.
PIN ASSIGNMENTS--Fig. 3.5.2-7
POWER SUPPLIES--SINGLE OR DUAL SUPPLY DESIGN

3.5.2.7 - 4Mb TO 32Mb DENSITY BY 8 & 16 Dual Supply Flash EEPROM in 8 X 6 GRID Micro BGA Package

CAPACITY--512K, 1024K, 2048K, & 4096K WORDS OF 8 BITS
CAPACITY--256K, 512K, 1048K, & 2048K WORDS OF 16 BITS
PACKAGE--8 X 6 GRID MICRO BGA PACKAGE, 0.75 mm BUMP PITCH
PIN ASSIGNMENTS--Fig. 3.5.2-8

3.5.2.8 - 16Mb TO 64Mb DENSITY BY 8 & 16, Dual supply Flash EEPROM in 8 X 9 GRID Micro BGA Package

CAPACITY--2048 to 8192 WORDS OF 8 BITS

CAPACITY--1024 to 4096 WORDS OF 16 BITS

PACKAGE--8 X 9 GRID MICRO BGA PACKAGE, 0.75 mm BUMP PITCH

PIN ASSIGNMENTS--Fig. 3.5.2-9

3.5.2.9 - 8Mb TO 128Mb DENSITY BY 8 & 16 Single or Dual Supply Flash EEPROM with 1Mb TO 8Mb DENSITY SRAM, Mixed Technology Multi Chip amemory Devices in 8 X 8 GRID Micro BGA Package

CAPACITY--1M, 2M, 4M, 8M, & 16M WORDS OF 8 BITS

OR

512K, 1M, 2M, 4M, & 8M, WORDS OF 16 BITS OF FEEPROM
COMBINED WITH

128K, 256K, 512K, OR 1048K WORDS OF 8 BITS

OR

64K, 128K, 256K, OR 512K WORDS OF 16 BITS OF SRAM

PACKAGE--8 X 8 GRID MICRO BGA PACKAGE, 0.8 mm BUMP PITCH

APPROVED COMBINATIONS OF FEEPROM & SRAM--Fig. 10A

PIN ASSIGNMENTS--Fig. 3.5.2-10B⇒Fig. 3.5.2-10E, Single Supply EEPROM

PIN ASSIGNMENTS--Fig. 3.5.2-10F⇒Fig. 3.5.2-10J, Dual Supply EEPROM

3.5.2.10 - 4M TO 64M, BY 16 SINGLE SUPPLY FEEPROM IN TSOP1 (64 Mb TO 1 Gb DENSITY)

CAPACITY--4M, 8M, 16M, 32M, OR 64M, WORDS OF 16 BITS

PACKAGE--56 PIN TSOP1, 10.2 mm X 13.5 mm with 0.8 mm PP.

PIN ASSIGNMENTS--Fig. 3.5.2-11

POWER SUPPLIES--SINGLE SUPPLY DESIGN

3.5.2.11 - 2M TO 64M BY 16, Single Supply Flash EEPROM IN FBGA Package (32 Mb TO 1 Gb DENSITY)

CAPACITY--2M, 4M, 8M, 16M, 32M, OR 64M WORDS OF 16 BITS

PACKAGE--8 X 8 Fine Pitch BGA

PIN ASSIGNMENTS--Fig. 3.5.2-12

POWER SUPPLIES--SINGLE SUPPLY DESIGN

3.5.2.12 - 4M, 8M, & 16M BY 16 FLASH EEPROM IN TSOP2 AND FBGA with SDRAM INTERFACE

CAPACITY -- 4M, 8M, OR 16M WORDS OF 16 BITS

PACKAGE -- 54 PIN TSOP2, 10.16 mm Wide, 0.8 mm Pin Pitch

PACKAGE -- 60 Ball FBGA, 0.8 mm Pitch

PIN ASSIGNMENTS -- IN TSOP2, Fig. 3.5.2 -13

PIN ASSIGNMENTS -- IN FBGA, Fig. 3.5.2 -14

POWER SUPPLIES -- SINGLE SUPPLY DESIGN

3.5.2.13 - 8M TO 256M BY 16 AND 4M TO 128M BY 32 FEEPROM IN SSOP
FIGURE 3.5.2-15

CAPACITY--User selectable as:

8M, 16M, 32M, 64M, 128M. and 256M WORDS OF 16 BITS or
4M, 8M, 16M, 32M, 64M, and 128M WORDS OF 32 BITS

PACKAGE--90 PIN SSOP, 13.3 mm WIDE

PIN ASSIGNMENTS--Fig. 3.5.2-15

POWER SUPPLIES--OPTIONAL, SINGLE OR DUAL SUPPLY DESIGN

3.5.2.14 - SINGLE-SUPPLY 16Mb AND 32Mb (x16/x32) FEEPROM IN 80-PIN PQFP
FIGURE 3.5.2-16

CAPACITY--User selectable as:

1M and 2M WORDS OF 16 BITS or
512K and 1M WORDS OF 32 BITS

PACKAGE--80 PIN PQFP

PIN ASSIGNMENTS--Fig. 3.5.2-16A

POWER SUPPLIES-- SINGLE SUPPLY DESIGN

3.5.2.15 - 128Mb TO 1Gb (x8/x16) FEEPROM IN 64-BALL LBGA

CAPACITY--User selectable as:

512M and 1G WORDS OF 8 BITS or
128M and 256M WORDS OF 16 BITS

PACKAGE--64-BALL LBGA, 1.0 mm PITCH

PIN ASSIGNMENTS--Fig. 3.5.2-17

3.5.2.16 - 128Mb TO 1Gb (x8/x16) FEEPROM IN 64-BALL LBGA

CAPACITY--User selectable as:

512M and 1G WORDS OF 8 BITS or
128M and 256M WORDS OF 16 BITS

PACKAGE--64-BALL TFBGA, 1.0 mm PITCH

PIN ASSIGNMENTS--Fig. 3.5.2-18

3.5.2.17 - 16Mb TO 512Mb (x8/x16) FEEPROM IN 52-PIN TSOP II

CAPACITY--User selectable as:

128M, 256M, and 512M WORDS OF 8 BITS or
16M, 32M, and 64M WORDS OF 16 BITS

PACKAGE--52-PIN TSOP II, 0.40 mm PITCH

PIN ASSIGNMENTS--Fig. 3.5.2-19

**3.5.2.18 - 16Mb TO 512Mb (x16) Synchronous 1.8V / 3.0V FEEPROM IN
56-PIN TSOP I**

CAPACITY--User selectable as:

1M, 2M, 4M, 8M, 16M, and 32M WORDS OF 16 BITS

PACKAGE--56--PIN TSOP I, 0.50 mm PITCH

PIN ASSIGNMENTS--Fig. 3.5.2-20

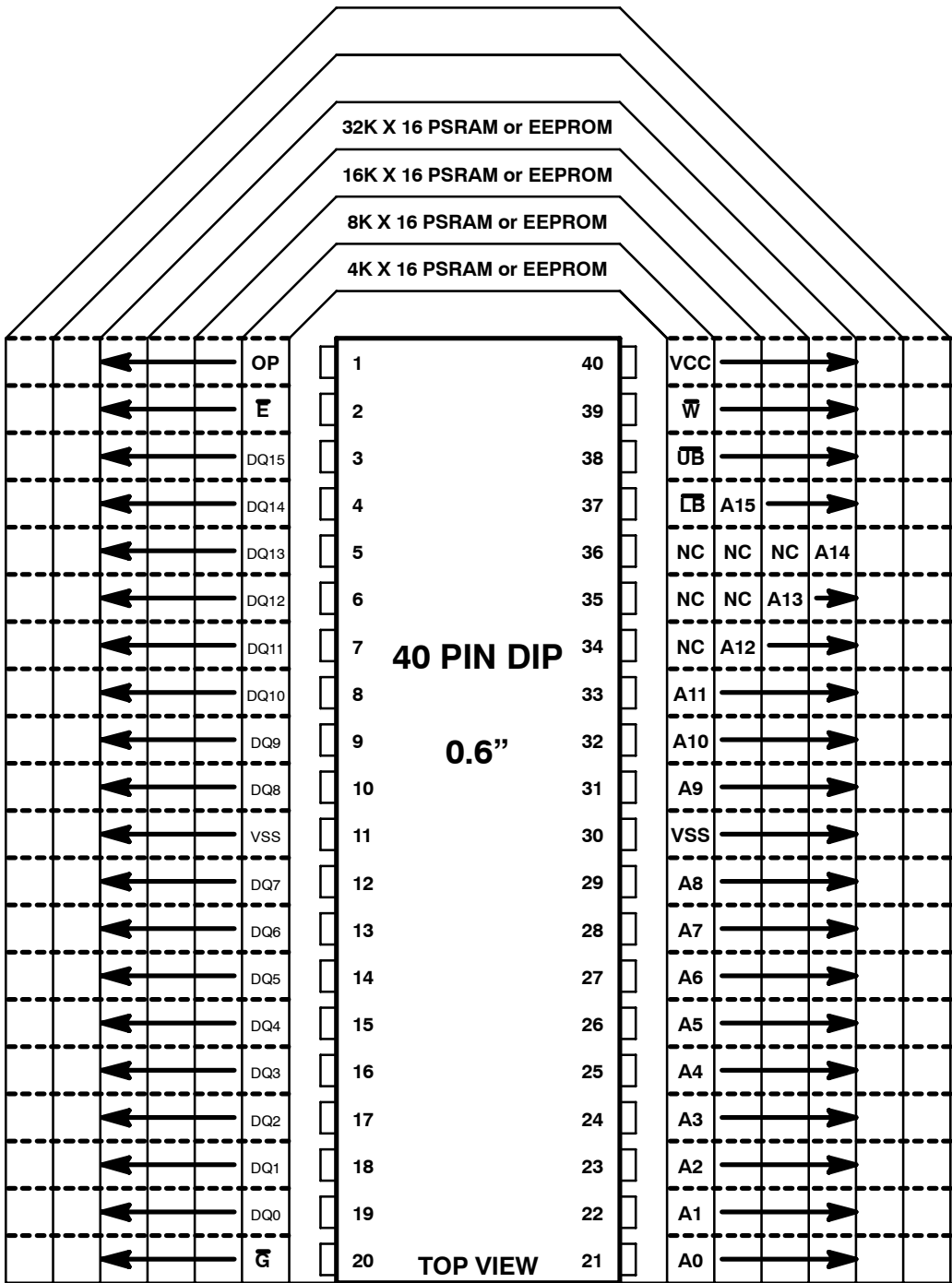
**3.5.2.19 - 16Mb TO 1Gb (x16) Synchronous 1.8V / 3.0V FEEPROM IN
64-BALL LFBGA**

CAPACITY--User selectable as:

1M, 2M, 4M, 8M, 16M, 32M, and 64M WORDS OF 16 BITS

PACKAGE--64--BALL LFBGA 1.0 mm BALL PITCH

PIN ASSIGNMENTS--Fig. 3.5.2-21



‘FIGURE 3.5.2-1
4K TO 32K BY 16 EEPROM FAMILY IN DIP

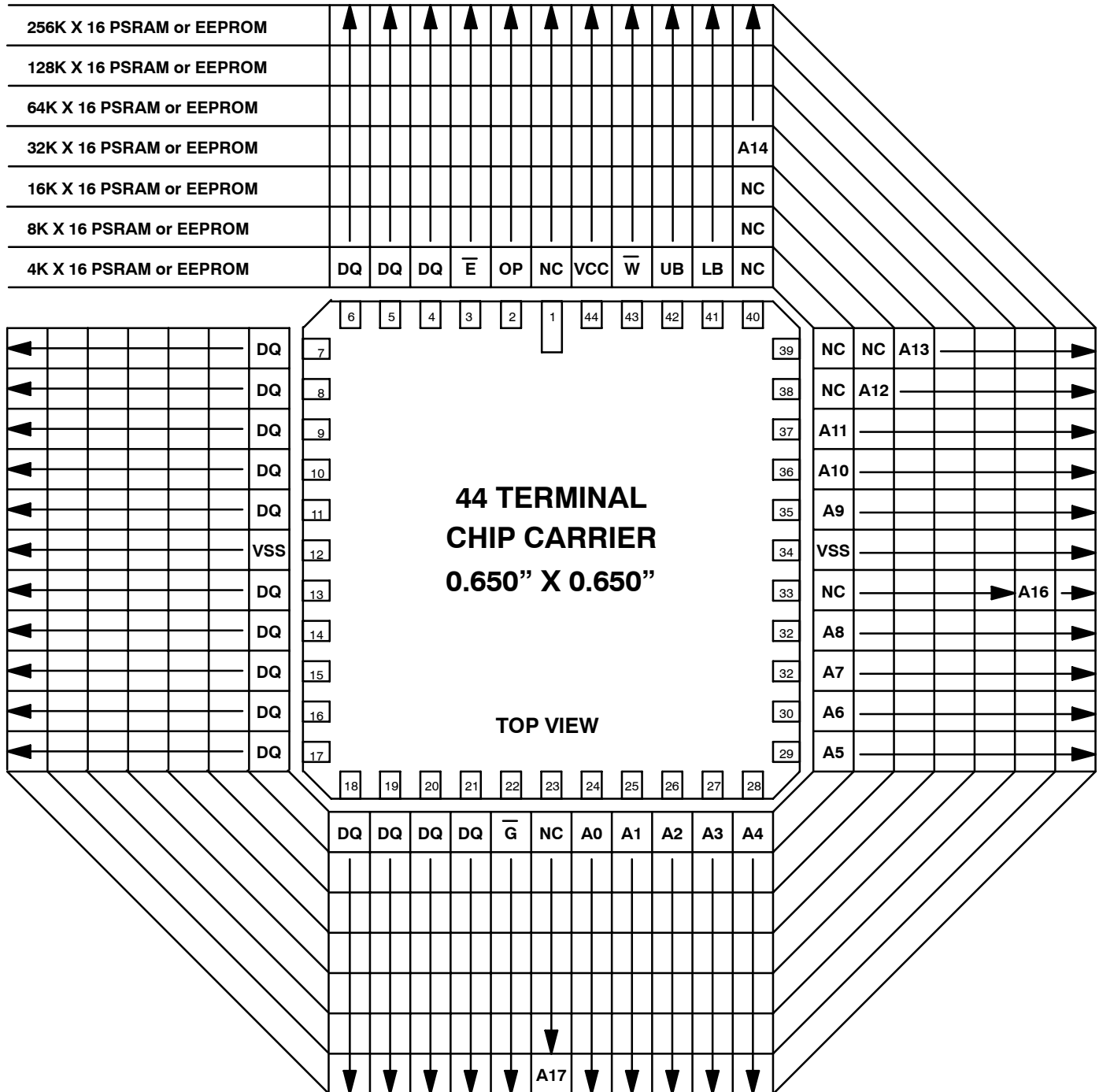


**FIGURE 3.5.2-2
4K TO 256K BY 16 EEPROM FAMILY IN SCC**

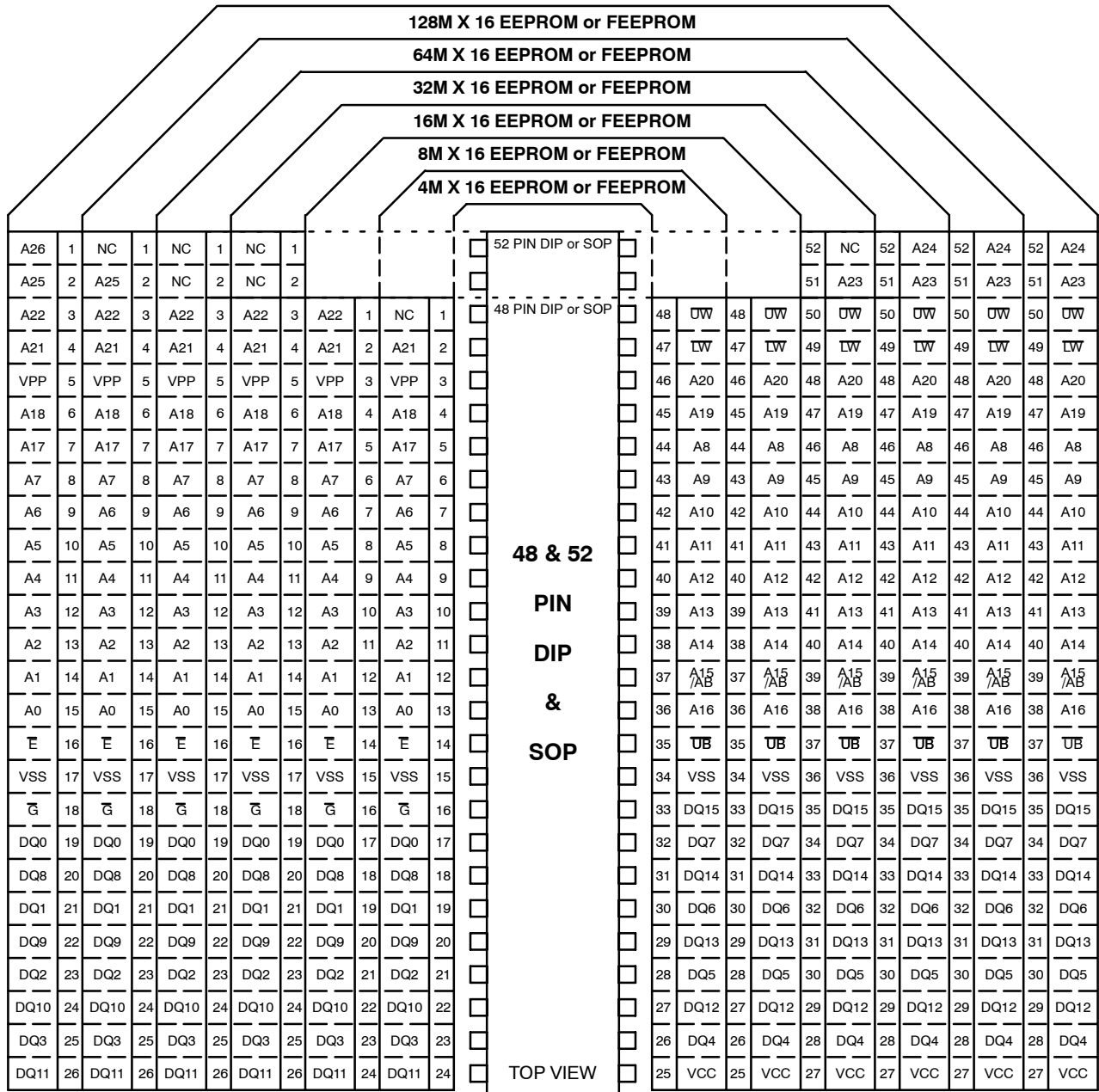
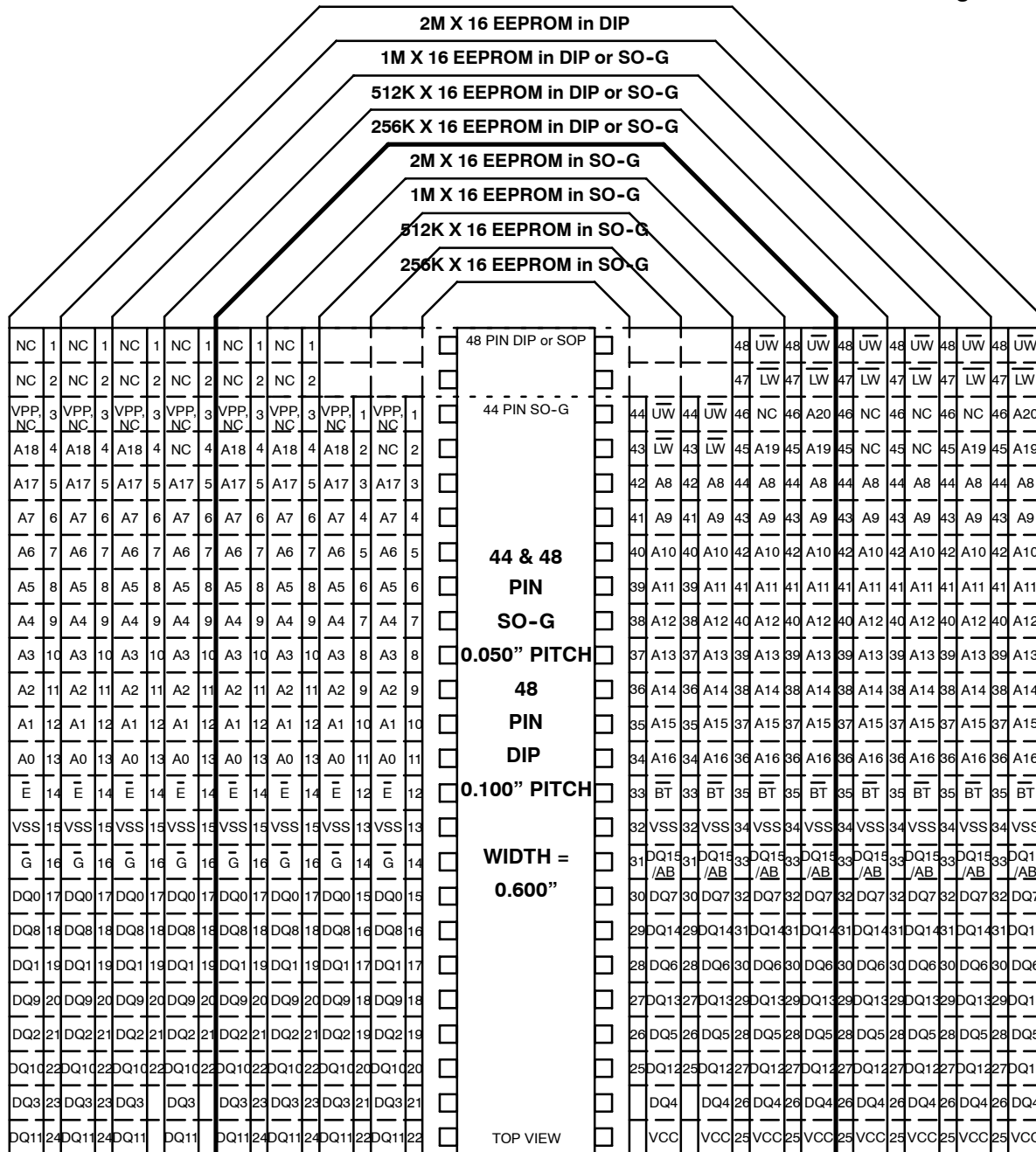
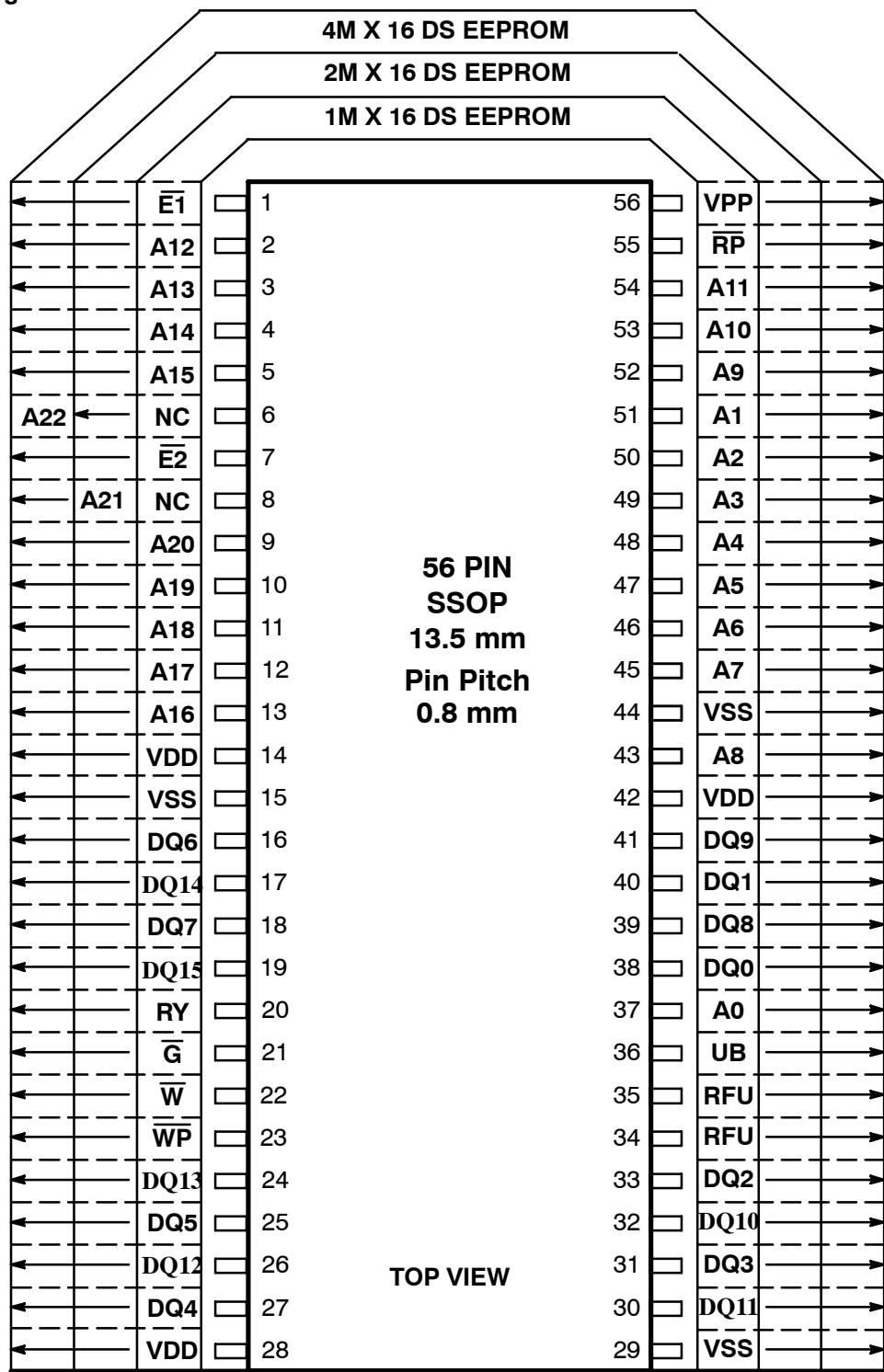


FIGURE 3.5.2-3
4M TO 128M BY 16 EEPROM or FEEPROM FAMILY IN DIP AND SOP



AB: ADDRESS INPUT, UPPER/LOWER BYTE SELECT
BT: BYTE MODE ENABLE

FIGURE 3.5.2-4
256K TO 2M BY 16 EEPROM IN DIP AND SO-G



	UB	A0	DQ0 ⇒ DQ7	DQ8 ⇒ DQ15
Word Access	V _{IH}	X	Even Byte	Odd Byte
Odd Byte Access	V _{IL}	V _{IH}	Odd Byte	High Z

FIGURE 3.5.2-5
1M TO 4M BY 16 DUAL SUPPLY EEPROM IN SOP

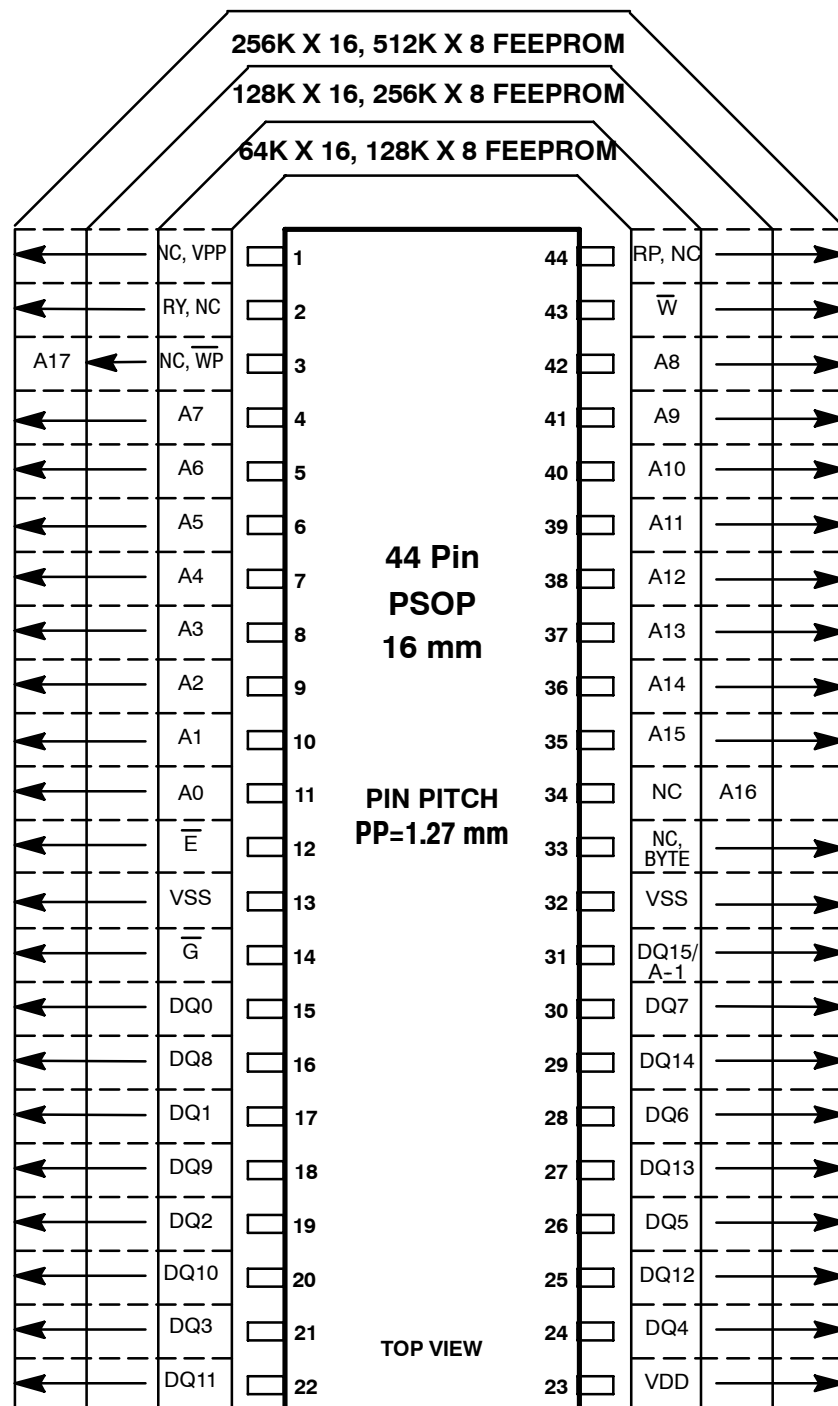


FIGURE 3.5.2-6
1M, 2M, & 4M DENSITY BY 8 & 16 SINGLE OR DUAL SUPPLY
FEEPROM IN PSOP, 128K TO 512K BY 8 OR 64K TO 256K BY 16